Electronic Switch Arrays for Managing Microbattery Arrays

Array circuitry is dynamically configured to optimize performance and disconnect defective elements.

NASA's Jet Propulsion Laboratory, Pasadena, California

Integrated circuits have been invented for managing the charging and discharging of such advanced miniature energy-storage devices as planar arrays of microscopic energy-storage elements [typically, microscopic electrochemical cells (microbatteries) or microcapacitors]. The architecture of these circuits enables implementation of the following energy-management options:

- Dynamic configuration of the elements of an array into a series or parallel combination of banks (subarrays), each array comprising a series or parallel combination of elements;
- Direct addressing of individual banks for charging and/or discharging; and
- Disconnection of defective elements and corresponding reconfiguration of the rest of the array to utilize the remaining functional elements to obtain the desired voltage and current performance.

One of the reasons for fabricating microbattery and microcapacitor arrays is that the array form affords partial immunity to defects in individual energy-storage elements. Defective energy-storage elements act as loads on the functional ones, thereby reducing the capacity of an overall array. By enabling the disconnection of defective elements and reconfiguration of the rest of the array, the present invention offers practical means to realize this partial immunity. In addition, the invention provides for interrogating individual cells and banks in the array and charging them at the current-vs.-time or voltage-vs.-time characteristics needed for maximizing the life of the array.

An integrated circuit according to the invention consists partly of a planar array of field-effect transistors that function as switches for routing electric power among the energy-storage elements, the power source, and the load (see figure). To connect the energy-storage elements to the power source for charging, a specific subset of switches is closed; to connect the energy-storage elements to the load for discharging, a different specific set of switches is closed.

The aforementioned monitoring, testing, state-setting, and trip-current-setting functions would be effected by circuitry on an integrated-circuit card inside the housing. Also on the card would be (1) input and output circuitry for remote monitoring and control and (2) a tag random-access memory as an electronic means of identifying the system by serial number, location, a reference designation, and operational characteristics.

This work was done by Terry Greenfield of ASRC Aerospace Corp. for Kennedy Space Center. For further information, contact the Kennedy Innovative Partnerships Program Office at (321) 861-7158. KSC-12742
responding locations on, and as an integral part of, this integrated circuit; or (2) following a flip-chip approach, fabricate the array of energy-storage elements on a separate integrated-circuit chip and then align and bond the two chips together.

This work was done by Mohammad Mojarradi, Mahmoud Alahmad, Vinesh Sukumar, Fadi Zghoul, Kevin Buch, Herbert Hess, Harry Li, and David Cox of Caltech for NASA’s Jet Propulsion Laboratory. Further information is contained in a TSP (see page 1).

In accordance with Public Law 96-517, the contractor has elected to retain title to this invention. Inquiries concerning rights for its commercial use should be addressed to:

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Lower-Dark-Current, Higher-Blue-Response CMOS Imagers

Semiconductor junctions are relocated away from Si/SiO₂ interfaces.

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Several improved designs for complementary metal oxide/silicon (CMOS) integrated-circuit image detectors have been developed, primarily to reduce dark currents (leakage currents) and secondarily to increase responses to blue light and increase signal-handling capacities, relative to those of prior CMOS imagers. The main conclusion that can be drawn from a study of the causes of dark currents in prior CMOS imagers is that dark currents could be reduced by relocating p/n junctions away from Si/SiO₂ interfaces. In addition to reflecting this conclusion, the improved designs include several other features to counteract dark-current mechanisms and enhance performance.

The left half of the figure illustrates two of the improved designs, in which p-doped implants are added, variously, underneath and/or at the edges of the field oxide regions. These implants hold the Si/SiO₂ interfaces in thermal equilibrium and prevent generation of dark current at the interfaces. In covering the field oxide, the p implants separate the p/n junctions from the Si/SiO₂ interfaces, so that the interfacial component of the dark current (which is the major component) is greatly reduced.

Beyond a certain electric strength, the leakage current depends very strongly on the strength of the electric field. In order to reduce electric fields in the reverse-biased junctions, the p wells are separated from the n wells. A double n well in each pixel is preferred, both for increased photocarrier-collection efficiency and for tailoring the doping so that the electric field in the transition region between p+ to n well region is low.

For electrical connections to the photodiodes, which also act as the sources of reset field-effect transistors, n+ implants are necessary. Unfortunately, the p+/n' junctions heretofore associated with such implants are undesirable because they contain high electric fields, which give rise to significant tunneling currents, which, in turn, are components of dark currents. In these designs, p implants are added at the surfaces to tailor the doping from p+ accumulation layers to n' source layers, thereby reducing tunneling currents.

Two of the improved designs illustrated in the right half of the figure follow an alternative approach to tailoring the doping so that the electric field at the interface is low. In these designs, p implants are added at the surfaces to tailor the doping from p+ accumulation layers to n' source layers, thereby reducing tunneling currents.

These Cross Sections of a Pixel in a CMOS imager represent four designs that provide for reduction of dark currents in different ways.